

L Number	Hits	Search Text	DB	Time stamp
10	1	6558239.pn.	USPAT; US-PGPUB; EPO; JPO	2004/08/12 11:10
63	1	"20040106364"	USPAT; US-PGPUB; EPO; JPO	2004/08/12 11:37
75	17	5688360.URPN.	USPAT	2004/08/12 11:47
76	98	polishing near2 (station stations) same (cleaning scrubbing) near2 (station stations)	USPAT; US-PGPUB; EPO; JPO	2004/08/12 12:13
-	458	polishing with cleaning with system	USPAT; US-PGPUB; EPO; JPO	2004/08/11 16:48
-	1642	(wafer wafers) and polishing and cleaning and (cylinders cylindrical)	USPAT; US-PGPUB; EPO; JPO	2004/08/11 18:04
-	299	156/345.12.ccls.	USPAT; US-PGPUB; EPO; JPO	2004/08/11 17:01
-	210	451/190.ccls.	USPAT; US-PGPUB; EPO; JPO	2004/08/11 17:03
-	42	("3978580"   "4094058"   "4653864"   "4685180"   "4691995"   "4775225"   "5247377"   "5263888"   "5379139"   "5406989"   "5499128"   "5507323"   "5511591"   "5539545"   "5548429"   "5642214"   "5680189"   "5742370"   "5757451"   "5852484"   "5854664"   "5861932"   "5875922"   "5952676"   "5956112"   "6001203"   "6011609"   "6016178"   "6016181"   "6055035"   "6163357"   "6219126"   "6226067"   "6236445"   "6304306"   "6304311"   "6319100"   "6325704"   "6337730"   "6361867"   "6414733"   "6565421"   "2001/0021000").PN.	USPAT	2004/08/11 17:10
-	389	451/194.ccls.	USPAT; US-PGPUB; EPO; JPO	2004/08/11 17:17
-	403	451/178.ccls.	USPAT; US-PGPUB; EPO; JPO	2004/08/12 11:37
-	421	((wafer wafers) and polishing and cleaning and (cylinders cylindrical)) and 451/\$.ccls.	USPAT; US-PGPUB; EPO; JPO	2004/08/11 18:06